GLOSSARY

R_b:
Resistance through the bulk material.

R_g:
Resistance to ground.

R_s:
Surface resistance

R_v:
Volume resistance

Ω:
Ohm

A-Static:
Former name of low charging material.

Antistatic:
First name of low charging material. Still used in common language (much more than the replacement "A-static").

CBM:
Charged Board Model.

CDM:
Charged Device Model.

Conductive:
See electrostatic conductive.

Dissipative:
See electrostatic dissipative.

ECU:
Electronic Controller Unit.

Electrostatic conductive:
Packaging with a surface resistance between 1 X10^2 Ω and < 1 X 10^5 Ω.

Electrostatic discharge (ESD):
Transfer of charge between bodies at different electrostatic potentials caused by direct contact or induced by electrostatic field.

Electrostatic discharge sensitive device (ESDS):
Discrete device, integrated circuit or assembly that may be damaged by electrostatic fields or electrostatic discharge encountered in routine handling, testing or transit

Electrostatic discharge shielding:
Barrier or enclosure that limits the passage of current and attenuates the energy resulting from an electrostatic discharge such that the maximum energy from 1 000 V human body model discharge is less than or equal to 50 nJ.

Electrostatic dissipative:
Packaging with a surface resistance $\geq 1 \times 10^{5}\ \Omega$ and $< 1 \times 10^{11}\ \Omega$.

EOS:
Electrical Overstress

EPA:
See ESD protected area (EPA).

ESD:
See Electrostatic discharge.

ESD protected area (EPA):
Area in which ESDS can be handled with accepted risk of damage as a result of electrostatic discharge or fields.

ESDS:
See Electrostatic discharge sensitive device.

ESD sensitivity:
Maximum voltage at which the ESDS does not suffer any ESD damage.

FCDM:
Field induced Charged Device Model.

FFB:
Field From Board Model.

FIM:
Field Induced Model.

Ground:
Conducting mass of the earth whose electric potential at any point is conventionally taken at zero.

HBM:
Human Body Model.

Insulating:
Packaging with a surface resistance $\geq 1 \times 10^{11}\ \Omega$.

Intimate packaging:
Material which makes contact with ESDS.

k:
Kilo.

Low charging:
packaging exhibiting properties which minimize any charge generation.

MOSFET:
Metal-Oxide-Semiconductor Field Effect Transistor.

PPM:
Parts Per Million.

Proximity packaging:
Material not making contact with ESDS but which is used to enclose one or more devices.

Static:
Opposite of anti-static, a-static or low charging. Meaning an insulator that is chargeable.

Tribo-electric charging:
Electrical charging process in which charge is generated by the contact and separation of two surfaces which may be solid, liquid or particulate-carrying gases.

V:
Volt(s).